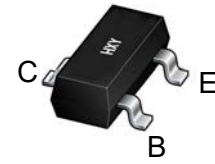




Features

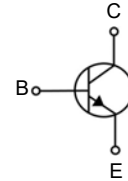
- Collector Current: $I_C=0.6A$
- Power Dissipation of 300mw



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBT2222A	SOT-23	1P	3000

SOT-23



Maxmim Ratings (Ta=25 unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V_{CBO}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	600	mA
Collector Power Dissipation	P_C	300	mW
Thermal Resistance From Junction To Ambient	$R_{\theta JA}$	417	$^{\circ}C/W$
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature	T_{stg}	-55~+150	$^{\circ}C$

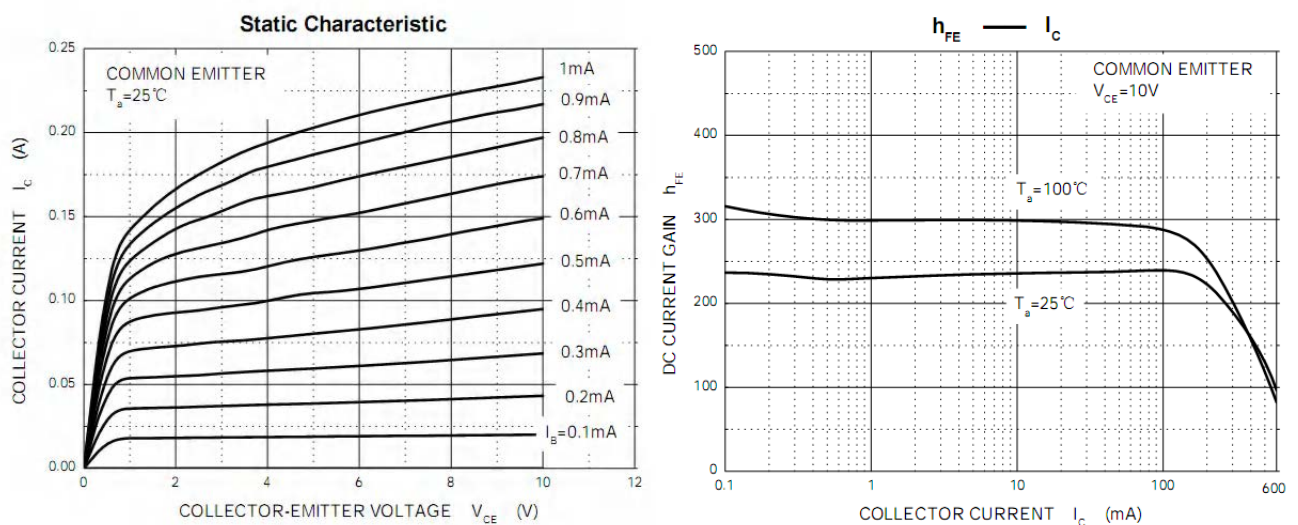


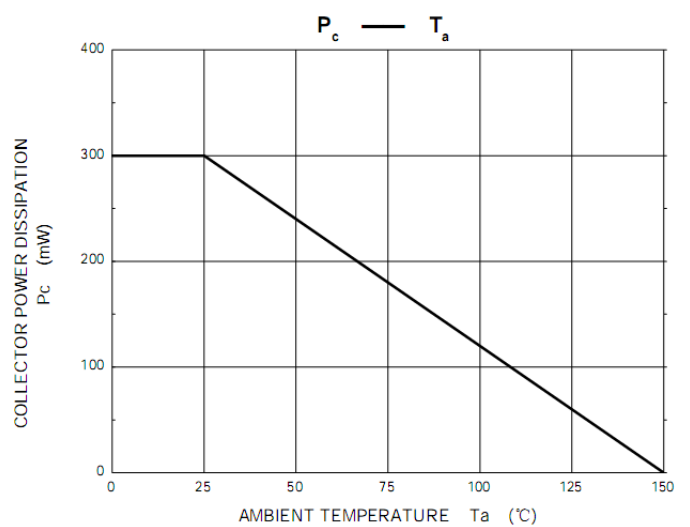
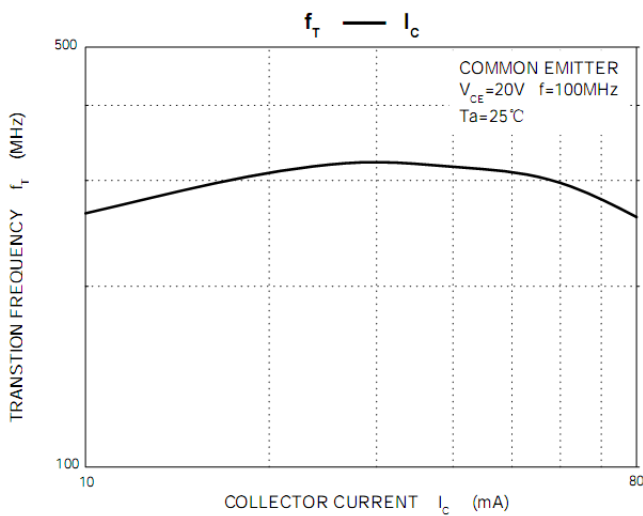
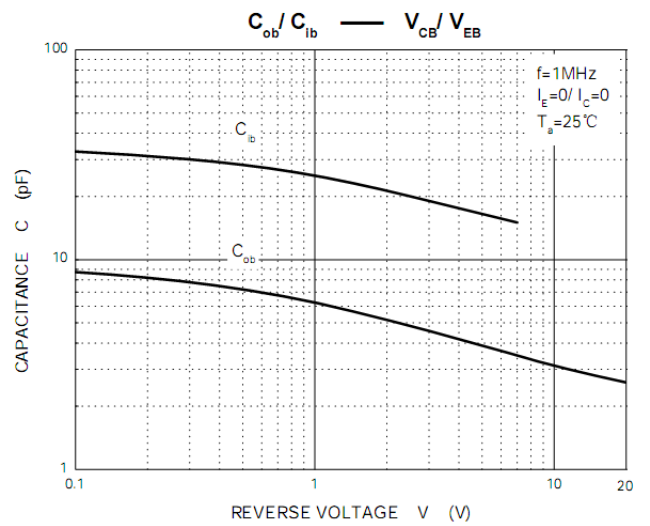
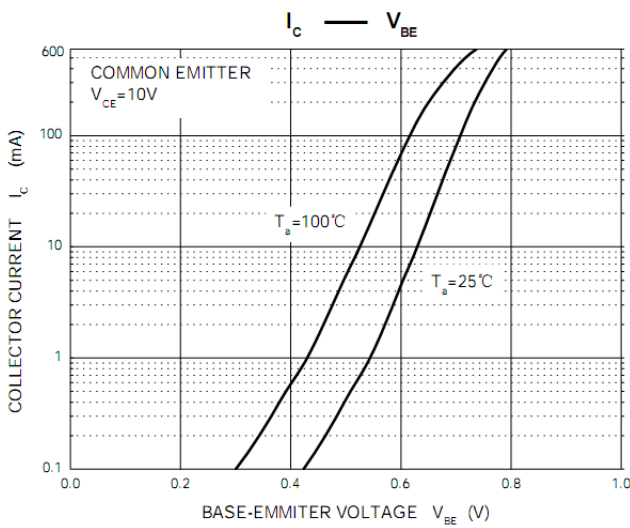
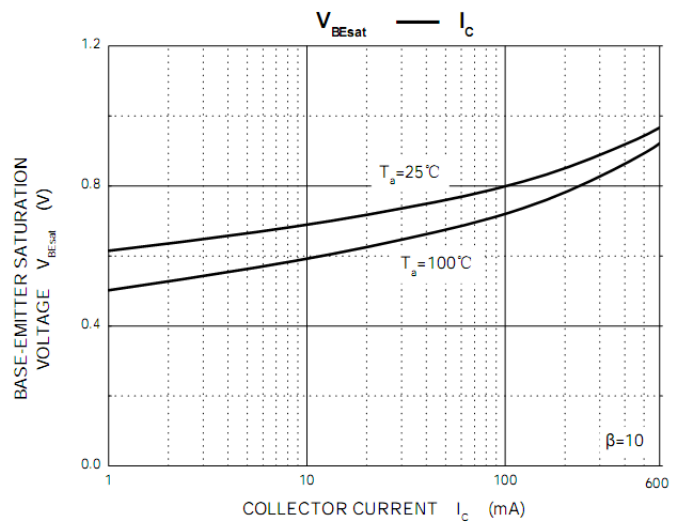
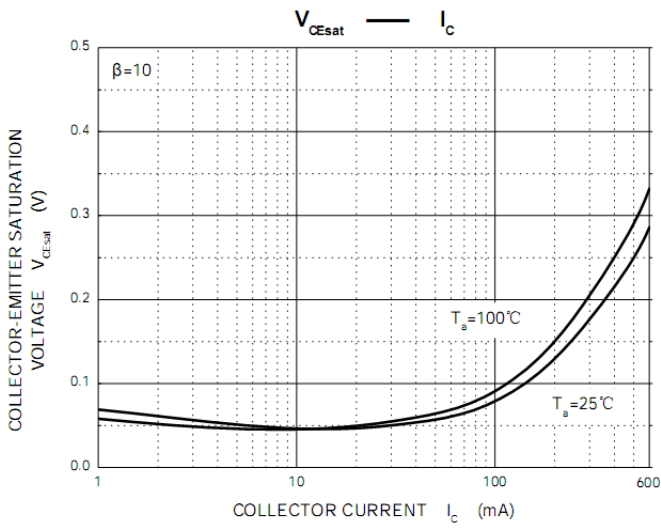
Electrcal Characteristics (Ta=25 unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=10\mu A, I_E=0$	75			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}^*$	$I_C=10mA, I_B=0$	40			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=10\mu A, I_C=0$	6			V
Collector cut-off current	I_{CBO}	$V_{CB}=60V, I_E=0$			0.01	μA
Collector cut-off current	I_{CEX}	$V_{CE}=30V, V_{BE(off)}=3V$			0.01	μA
Emitter cut-off current	I_{EBO}	$V_{EB}=3V, I_C=0$			0.1	μA
DC current gain	$h_{FE(1)}^*$	$V_{CE}=10V, I_C=150mA$	100		300	
	$h_{FE(2)}$	$V_{CE}=10V, I_C=0.1mA$	40			
	$h_{FE(3)}^*$	$V_{CE}=10V, I_C=500mA$	42			
Collector-emitter saturation voltage	$V_{CE(sat)}^*$	$I_C=500mA, I_B=50mA$ $I_C=150mA, I_B=15mA$			1 0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}^*$	$I_C=500mA, I_B=50mA$ $I_C=150mA, I_B=15mA$			2.0 1.2	V
Transition frequency	f_T	$V_{CE}=20V, I_C=20mA,$ $f=100MHz$	300			MHz
Delay time	t_d	$V_{CC}=30V, V_{BE(off)}=-0.5V$			10	ns
Rise time	t_r	$I_C=150mA, I_{B1}=15mA$			25	ns
Storage time	t_s	$V_{CC}=30V, I_C=150mA$			225	ns
Fall time	t_f	$I_{B1}=-I_{B2}=15mA$			60	ns

*pulse test: Pulse Width $\leq 300\mu s$, Duty Cycles $\leq 2.0\%$.

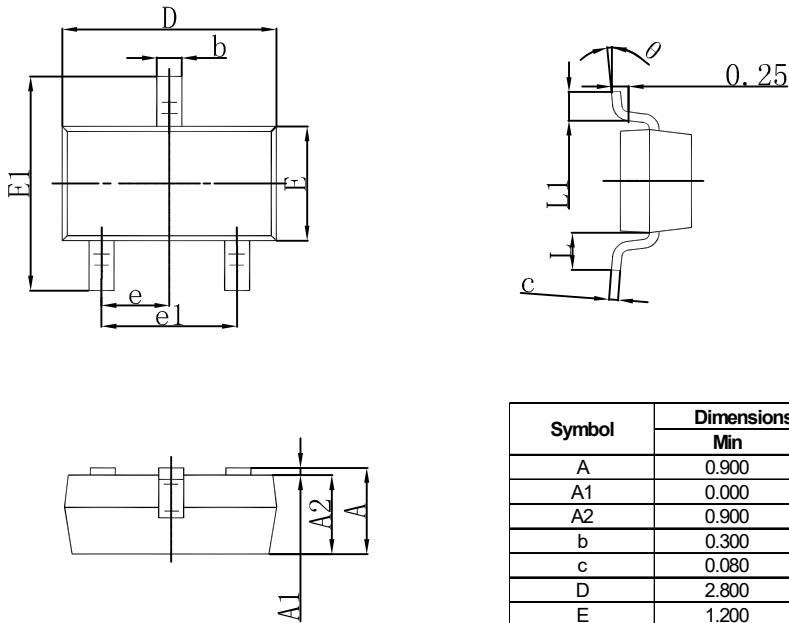
Typical Characteristics





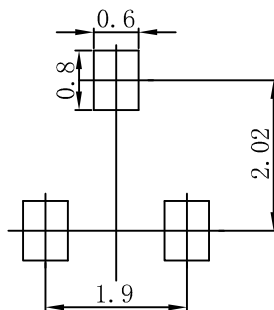


SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.



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